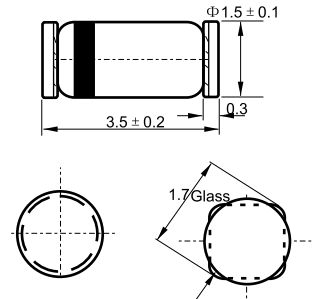




### MINI-MELF



Dimension in millimeters

### Features

- ✧ Small surface mounting type
- ✧ High reliability

### Applications

- ✧ Voltage stabilization

### Construction

- ✧ Silicon epitaxial planar

### Absolute Maximum Ratings

$T_j=25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Value	Unit
Power dissipation	$R_{thJA} \leq 300\text{K/W}$		$P_V$	500	mW
Z-current			$I_Z$	$P_V/V_Z$	mA
Junction temperature			$T_j$	175	$^\circ\text{C}$
Storage temperature range			$T_{stg}$	-65~+175	$^\circ\text{C}$

### Maximum Thermal Resistance

$T_j=25^\circ\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Junction ambient	on PC board 50mm × 50mm × 1.6mm	$R_{thJA}$	500	K/W

### Electrical Characteristics

$T_j=25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F=200\text{mA}$		$V_F$			1.5	V

Type	V <sub>Znom</sub>	I <sub>ZT</sub>	for V <sub>ZT</sub> and	r <sub>zIT</sub>	r <sub>zik</sub> at I <sub>ZK</sub>	I <sub>R</sub> and I <sub>R</sub> at V <sub>R</sub>	TK <sub>VZ</sub>
ZMM55C.	V	mA	V <sup>1)</sup>	Ω	Ω	mA	%/K
2V4	2.4	5	2.28~2.56	<85	<600	1	-0.09~-0.06
2V7	2.7	5	2.5~2.9	<85	<600	1	-0.09~-0.06
3V0	3.0	5	2.8~3.2	<90	<600	1	-0.08~-0.05
3V3	3.3	5	3.1~3.5	<90	<600	1	-0.08~-0.05
3V6	3.6	5	3.4~3.8	<90	<600	1	-0.08~-0.05
3V9	3.9	5	3.7~4.1	<90	<600	1	-0.08~-0.05
4V3	4.3	5	4.0~4.6	<90	<600	1	-0.06~-0.03
4V7	4.7	5	4.4~5.0	<80	<600	1	-0.05~+0.02
5V1	5.1	5	4.8~5.4	<60	<550	1	-0.02~+0.02
5V6	5.6	5	5.2~6.0	<40	<450	1	-0.05~+0.05
6V2	6.2	5	5.8~6.6	<10	<200	1	0.03~0.06
6V8	6.8	5	6.4~7.2	<8	<150	1	0.03~0.07
7V5	7.5	5	7.0~7.9	<7	<50	1	0.03~0.07
8V2	8.2	5	7.7~8.7	<7	<50	1	0.03~0.08
9V1	9.1	5	8.5~9.6	<10	<50	1	0.03~0.09
10	10	5	9.4~10.6	<15	<70	1	0.03~0.1
11	11	5	10.4~11.6	<20	<70	1	0.03~0.11
12	12	5	11.4~12.7	<20	<90	1	0.03~0.11
13	13	5	12.4~14.1	<26	<110	1	0.03~0.11
15	15	5	13.8~15.6	<30	<110	1	0.03~0.11
16	16	5	15.3~17.1	<40	<170	1	0.03~0.11
18	18	5	16.8~19.1	<50	<170	1	0.03~0.11
20	20	5	18.8~21.2	<55	<220	1	0.03~0.11
22	22	5	20.8~23.3	<55	<220	1	0.04~0.12
24	24	5	22.8~25.6	<80	<220	1	0.04~0.12
27	27	5	25.1~28.9	<80	<220	1	0.04~0.12
30	30	5	28~32	<80	<220	1	0.04~0.12
33	33	5	31~35	<80	<220	1	0.04~0.12
36	36	5	34~38	<80	<220	1	0.04~0.12
39	39	2.5	37~41	<90	<500	0.5	0.04~0.12
43	43	2.5	40~46	<90	<600	0.5	0.04~0.12
47	47	2.5	44~50	<110	<700	0.5	0.04~0.12
51	51	2.5	48~54	<125	<700	0.5	0.04~0.12
56	56	2.5	52~60	<135	<1000	0.5	0.04~0.12
62	62	2.5	58~66	<150	<1000	0.5	0.04~0.12
68	68	2.5	64~72	<200	<1000	0.5	0.04~0.12
75	75	2.5	70~79	<250	<1500	0.5	0.04~0.12

<sup>1)</sup> Tighter tolerances available request:

ZMM55A... ± 1% of V<sub>Znom</sub>

ZMM55B... ± 2% of V<sub>Znom</sub>

ZMM55F... ± 3% of V<sub>Znom</sub>

ZMM55C... ± 5% of V<sub>Znom</sub>

<sup>2)</sup> at T<sub>j</sub>=150 °C

### Characteristics ( $T_j=25^\circ\text{C}$ unless otherwise specified)

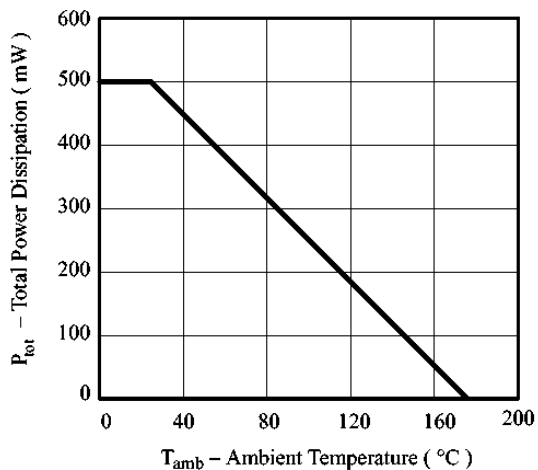


Figure 1. Total Power Dissipation vs. Ambient Temperature

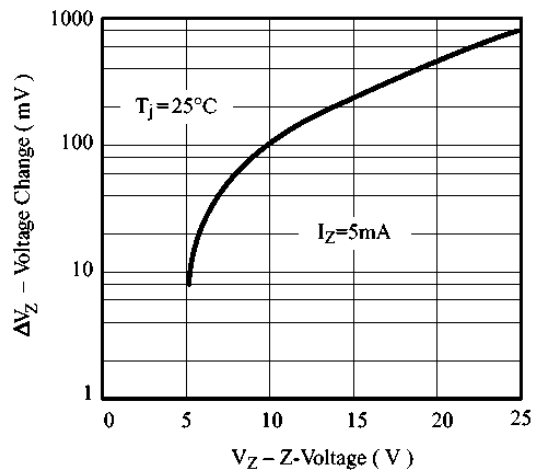


Figure 2. Typical Change of Working Voltage under Operating Conditions at  $T_{\text{amb}}=25^\circ\text{C}$

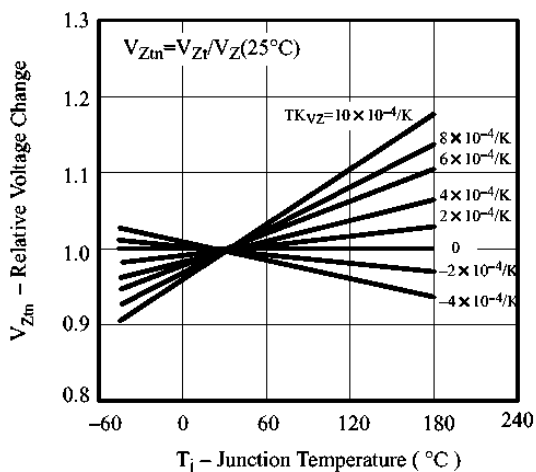


Figure 3. Typical Change of Working Voltage vs. Junction Temperature

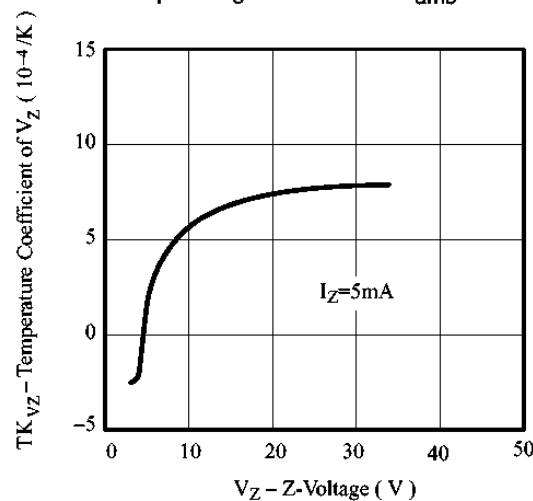


Figure 4. Temperature Coefficient of  $V_Z$  vs. Z-Voltage

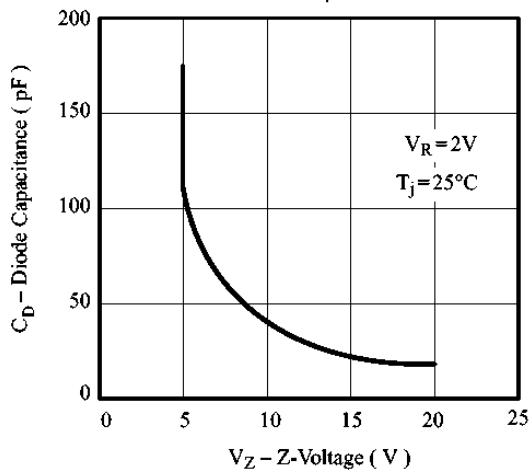


Figure 5. Diode Capacitance vs. Z-Voltage

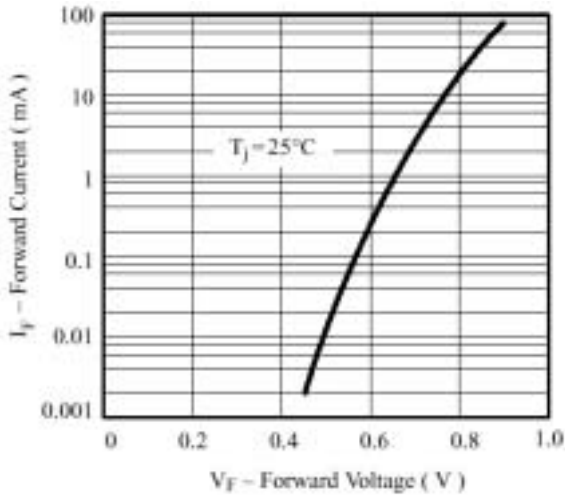


Figure 6. Forward Current vs. Forward Voltage

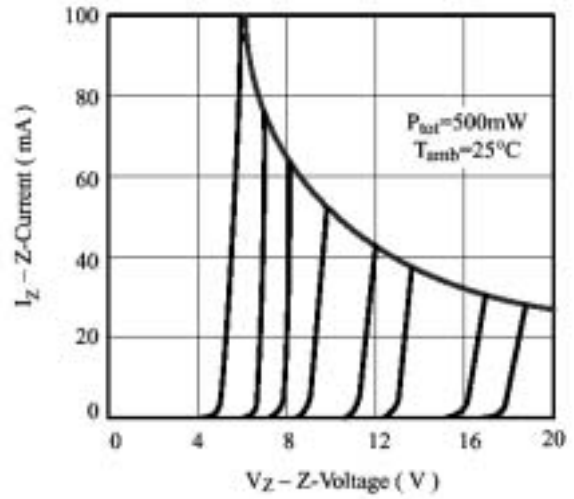


Figure 7. Z-Current vs. Z-Voltage

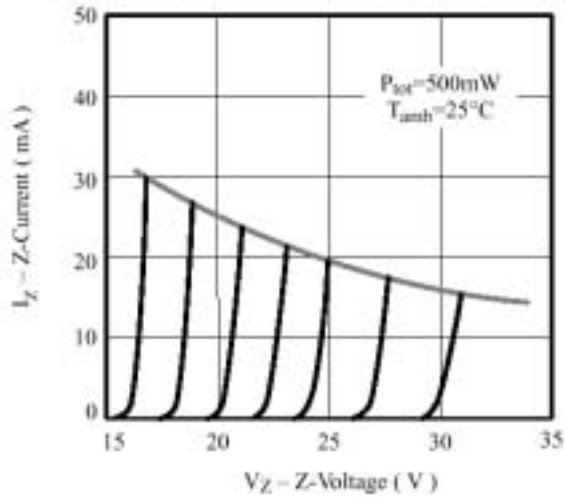


Figure 8. Z-Current vs. Z-Voltage

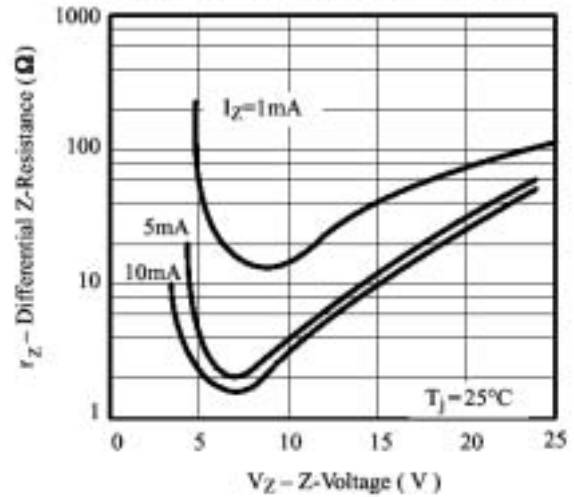


Figure 9. Differential Z-Resistance vs. Z-Voltage

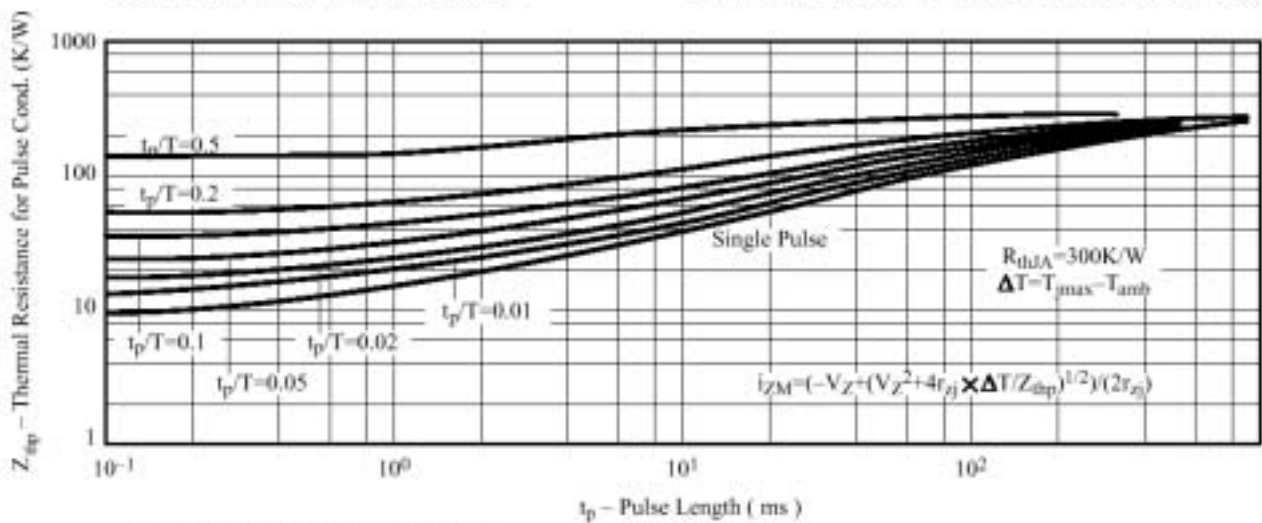


Figure 10. Thermal Response